

IRFW720B / IRFI720B

400V N-Channel MOSFET

General Description

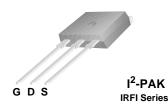
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

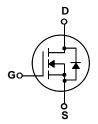
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and electronic lamp ballasts based on half bridge.

Features

- 3.3A, 400V, $R_{DS(on)}$ = 1.75 Ω @V_{GS} = 10 V Low gate charge (typical 14 nC)
- Low Crss (typical 11 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability







Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		IRFW720B / IRFI720B	Units
V_{DSS}	Drain-Source Voltage		400	V
I _D	Drain Current - Continuous (T _C = 25°C)	3.3	Α
	- Continuous (T _C = 100°	C)	2.1	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	13.2	Α
V_{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	240	mJ
I _{AR}	Avalanche Current	(Note 1)	3.3	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.9	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		49	W
	- Derate above 25°C	İ	0.39	W/°C
T _J , T _{stg}	Operating and Storage Temperature Rang	je	-55 to +150	°C
TL	Maximum lead temperature for soldering p 1/8" from case for 5 seconds	ourposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.57	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	racteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		400			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to	25°C		0.4		V/°C
I _{DSS}	Zana Cata Valtana Duain Councat	V _{DS} = 400 V, V _{GS} = 0 V				10	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 320 V, T _C = 125°C				100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V				-100	nA
On Cha	racteristics		<u> </u>				
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1.65 A			1.4	1.75	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 1.65 \text{ A}$	(Note 4)		2.8		S
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,			460	600	pF
Coss	Output Capacitance	f = 1.0 MHz			55	72	pF
C _{rss}	Reverse Transfer Capacitance				11	15	pF
Switchi	ng Characteristics						
t _{d(on)}	Turn-On Delay Time	V 000 V I 0 0 A			10	30	ns
t _r	Turn-On Rise Time	$V_{DD} = 200 \text{ V}, I_D = 3.3 \text{ A},$			35	80	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$			35	80	ns
t _f	Turn-Off Fall Time	(Ne	ote 4, 5)		35	80	ns
Qg	Total Gate Charge	V _{DS} = 320 V, I _D = 3.3 A,			14	18	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V			2.7		nC
Q _{gd}	Gate-Drain Charge		ote 4, 5)		5.6		nC
	ource Diode Characteristics a					2.2	^
l _S	Maximum Continuous Drain-Source Did					3.3	A
I _{SM}	Maximum Pulsed Drain-Source Diode F					13.2	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3.3 A				1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 3.3 \text{ A,}$	Note 4)		220		ns
Q_{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$	11010 7)		1.36		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 39mH, I_{AS} = 3.3A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 3.3A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

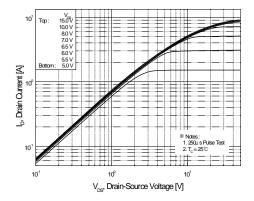


Figure 1. On-Region Characteristics

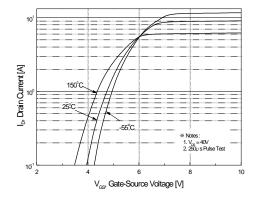


Figure 2. Transfer Characteristics

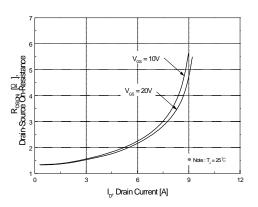


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

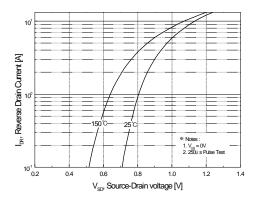


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

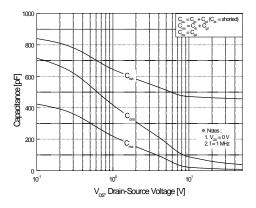


Figure 5. Capacitance Characteristics

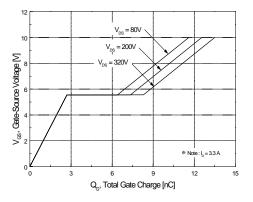


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

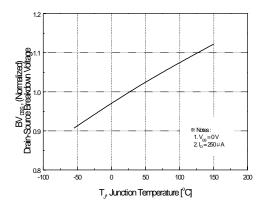


Figure 7. Breakdown Voltage Variation vs Temperature

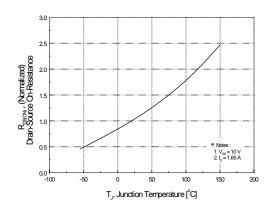


Figure 8. On-Resistance Variation vs Temperature

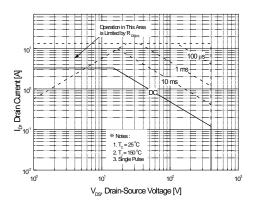


Figure 9. Maximum Safe Operating Area

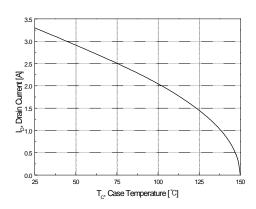


Figure 10. Maximum Drain Current vs Case Temperature

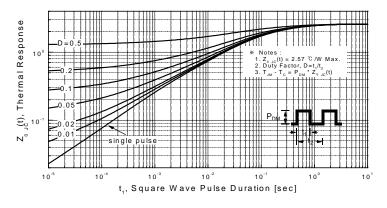
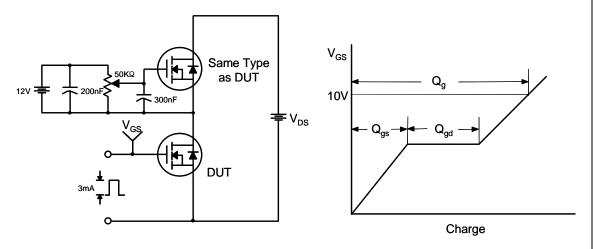


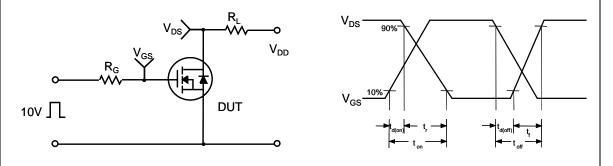
Figure 11. Transient Thermal Response Curve

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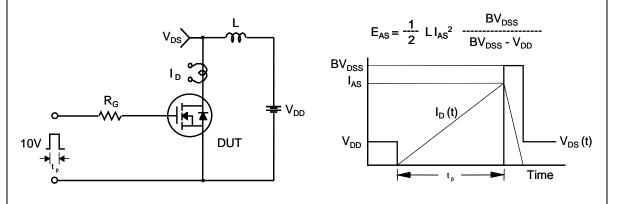
Gate Charge Test Circuit & Waveform



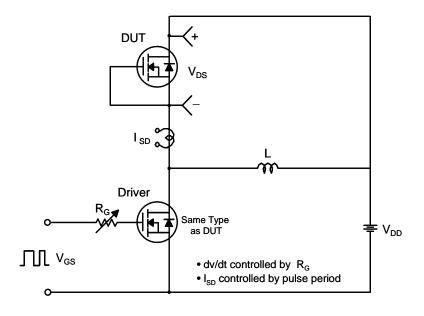
Resistive Switching Test Circuit & Waveforms

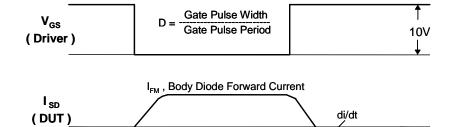


Unclamped Inductive Switching Test Circuit & Waveforms



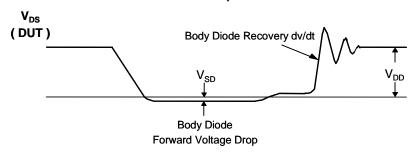
Peak Diode Recovery dv/dt Test Circuit & Waveforms



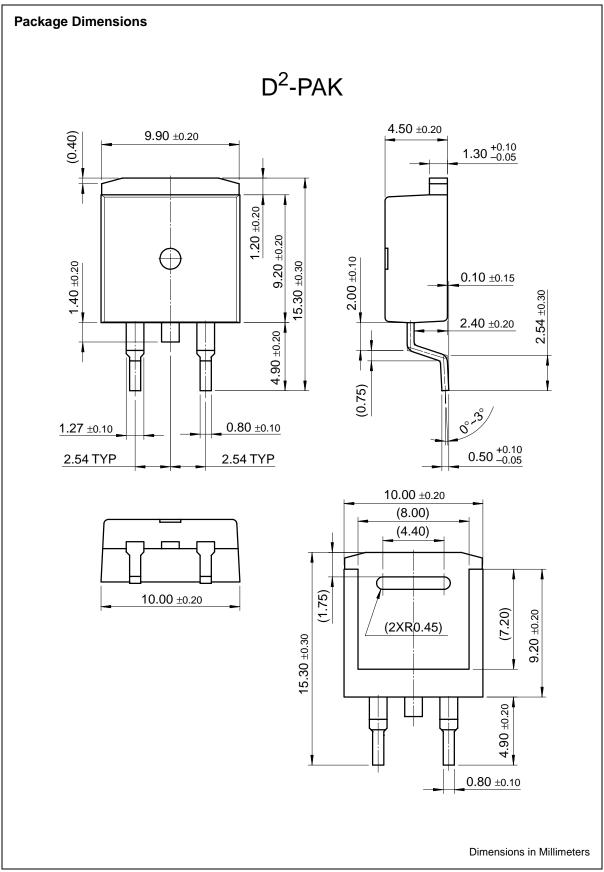


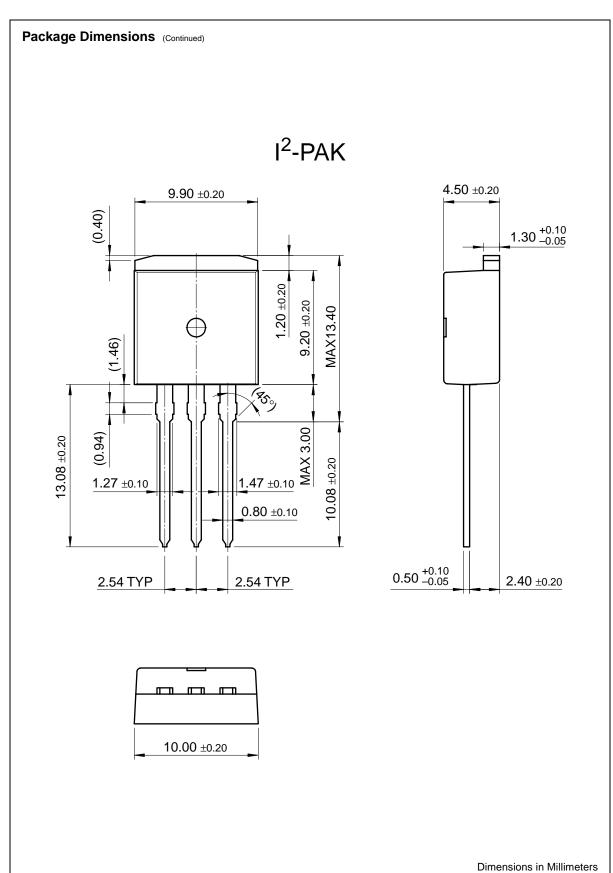
Body Diode Reverse Current

 I_{RM}



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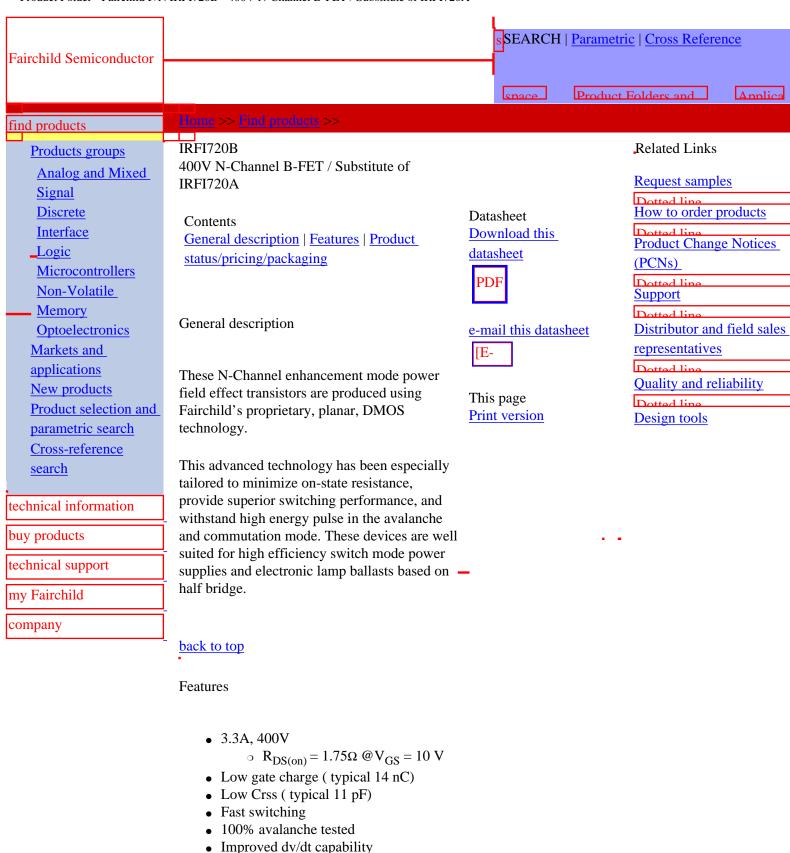
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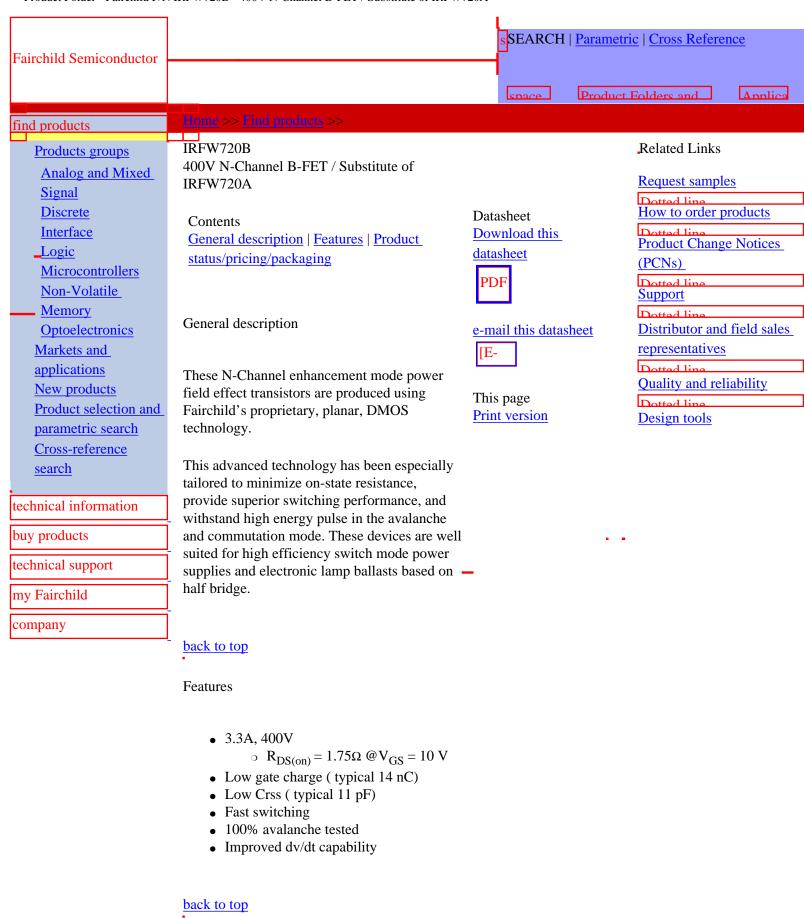
IRFI720BTU	Full Production	\$0.62	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

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Product Folder - Fairchild P/N IRFW720B - 400V N-Channel B-FET / Substitute of IRFW720A

IRFW720BTM	Full Production	\$0.62	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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